



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2020-09-21
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	giovanni giacopello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ESDCAN03-2BWY	HJW9*TAY03VC	A	9955	2020-09-21
	Amount	UoM	Unit type	ST ECOPACK Grade
	7	mg	Each	ECOPACK 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	CD00414548	



Package Designator	Size	Nbr of instances	Shape	
Not Applicable	2.00,1.26,0.93	3	shape	
Comment	SOT 323 - 3 LEADS			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
Exemption Id.	Description

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.77	die - leadframe	117047

QueryList : REACH-16th January 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration :						Mfr Item Name	HJW9*TAY03VC					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Dies	M-011 Other inorganic materials	0.226	mg	supplier	die	Silicon(Si)	7440-21-3		0.210	mg	929203	31964
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.004	mg	17699	609
				supplier	metallisation	Copper(Cu)	7440-50-8		0.002	mg	8850	304
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.001	mg	4425	152
				supplier	passivation	Silicon oxide	7631-86-9		0.006	mg	26549	913
				supplier	polymer coating	Polyimide	Proprietary		0.003	mg	13274	457
Leadframe	M-002 Other ferrous alloys, non-stainless steels	2.027	mg	supplier	alloy & coating	Nickel(Ni)	7440-02-0		0.769	mg	379378	117047
				supplier	alloy & coating	Iron(Fe)	7439-89-6		1.079	mg	532314	164231
				supplier	alloy & coating	Silicon(Si)	7440-21-3		0.002	mg	987	304
				supplier	alloy & coating	Cobalt (Co)	7440-48-4		0.009	mg	4440	1370
				supplier	alloy & coating	Silver (Ag)	7440-22-4		0.158	mg	77948	24049
				supplier	alloy & coating	Manganese (Mn)	7439-96-5		0.010	mg	4933	1522
Die attach	M-011 Other inorganic materials	0.037	mg	supplier	glue	Epoxyde bisphenol A resin	25068-38-6		0.003	mg	81082	457
				supplier	glue	Silica vitreous	60676-86-0		0.003	mg	81081	457
				supplier	glue	Ethoxyethoxy-ethyl acetate	112-15-2		0.008	mg	216216	1218
				supplier	glue	Aluminium oxide	1344-28-1		0.016	mg	432432	2435
				supplier	glue	Bisphenol A diglycidyl ether polymer	25036-25-3		0.006	mg	162162	913
				supplier	glue	Diaminodiphenylsulfone	proprietary		0.001	mg	27027	152
Bonding wires	M-004 Copper and its alloys	0.027	mg	supplier	wire	Copper(Cu)	7440-50-8		0.026	mg	962963	3957
				supplier	wire	Palladium(Pd)	7440-05-3		0.001	mg	37037	152
Encapsulation	M-011 Other inorganic materials	3.999	mg	supplier	mold compound	Silica vitreous	60676-86-0		3.411	mg	852962	519178
				supplier	mold compound	Epoxy Cresol Novolac	29690-82-2		0.220	mg	55014	33486
				supplier	mold compound	Phenol Resin	26834-02-6		0.200	mg	50013	30441
				supplier	mold compound	Tetrakis(2,6-dimethylphenyl) 1,3-phenylene b	139189-30-3		0.100	mg	25006	15221
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		0.060	mg	15004	9132
connections coating	Solder	0.254	mg	supplier	solder alloy	Carbon black	1333-86-4		0.008	mg	2001	1218
				supplier		Tin (Sn)	7440-31-5		0.254	mg	1000000	38661